

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4	"6924171".pn. or "5503286".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 09:56
L2	94222	(protrusions or posts or solders or bumps) near15 (distan\$3 or space\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 09:57
L3	19282	(protrusions or posts or solders or bumps) near15 (distan\$3 or space\$2) near15 (surface)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 09:57
L4	887	(protrusions or posts or solders or bumps) near15 (distan\$3 or space\$2) near15 (surface) near15 (recess)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:27
L5	0	(protrusions or posts or solders or bumps) near15 (distan\$3 or space\$2) near15 (surface) near15 (recess) near15 (microelectronic or micro-electronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 09:58
L6	0	(protrusions or posts or solders or bumps) near15 (distan\$3 or space\$2) near15 (surface) near15 (recess) with (microelectronic or micro-electronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 09:58
L7	0	(protrusions or posts or solders or bumps) near15 (distan\$3 or space\$2) near15 (surface) near15 (recess) same (microelectronic or micro-electronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 09:58
L8	96	(protrusions or posts or solders or bumps) near15 (distan\$3 or space\$2) near15 (surface) near15 (recess) same (element or component)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 09:59
L9	49	(protrusions or posts or solders or bumps) near15 (distan\$3 or space\$2) near15 (surface) near15 (recess) near15 (element or component)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:39

L10	22	9 and method	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:37
L11	44	8 and method	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:40
L12	64	(protrusions or posts or solders or bumps) with (distan\$3 or space\$2) near15 (surface) near15 (recess) near15 (element or component)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:39
L13	28	12 and method	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:42
L14	12624	(protrusions or posts or solders or bumps) near15 (surface) near15 (recess)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:56
L15	5856	14 and method	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:42
L16	151	15 and (microelectronic or micro-electronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:57
L17	2	16 and micro-meters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:43
L18	19	16 and micrometers	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:43
L19	1674	(protrusions or posts or solders or bumps) near15 (surface) near15 (recess) and mold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:01

L20	608	19 and (recess near15 mold)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:56
L21	21	20 and (microelectronic or micro-electronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:57
L22	5079	(protrusions or posts or solders or bumps) near15 (recess or pocket\$1) and (mold)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:02
L23	1580	22 and (pocket\$1 or recess) near15 (mold)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:02
L24	13	23 and ((method) with (microelectronic or micro-electronic))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:07
L25	2	"5244143".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:07
L26	3275	(protrusions or posts or solders or bumps) near15 (distan\$3 or space\$2) near15 (recess)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:29
L27	11	26 and ((method) with (microelectronic or micro-electronic))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:29
L28	48322	(protrusions or posts or solders or bumps) near15 (recess or pocket\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:36
L29	139	28 and ((method) with (microelectronic or micro-electronic))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:37

L30	48322	((protrusions or posts or solders or bumps) near15 (recess or pocket\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:37
L31	1034	((protrusions or posts or solders or bumps) near15 (recess or pocket\$1)) near25 (mold)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:37
L32	8	31 and ((method) with (microelectronic or micro-electronic))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:40
L33	2	"6924171".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:40